## **IGBT**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

#### **Features**

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

#### **Typical Applications**

- Inductive Heating
- Consumer Appliances
- Soft Switching

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	80 40	Α
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	320	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I <sub>F</sub>	80 40	Α
Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>FM</sub>	320	Α
Gate-emitter voltage	$V_{GE}$	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	$P_{D}$	260 104	W
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T <sub>stg</sub>	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

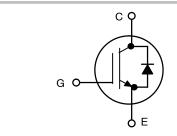
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

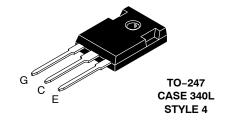


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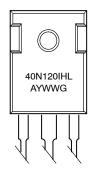
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40 A, 1200 V V<sub>CEsat</sub> = 1.90 V E<sub>off</sub> = 1.40 mJ





#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTB40N120IHLWG	TO-247 (Pb-Free)	30 Units / Rail

### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.48	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ hetaJC}$	1.5	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•			•		•
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V}, I_{C} = 500 \mu\text{A}$	V <sub>(BR)CES</sub>	1200	_	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 150°C	V <sub>CEsat</sub>	- -	1.90 2.1	2.35	V
Gate-emitter threshold voltage	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 400 μA	V <sub>GE(th)</sub>	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	$V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}$ $V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}, T_{J=150^{\circ}C}$	I <sub>CES</sub>	- -	_ _	0.5 2.0	mA
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	200	nA
DYNAMIC CHARACTERISTIC	•					•
Input capacitance		C <sub>ies</sub>	-	10400	_	pF
Output capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	-	245	-	
Reverse transfer capacitance	1	C <sub>res</sub>	-	185	=	
Gate charge total		$Q_g$		420		nC
Gate to emitter charge	V <sub>CE</sub> = 600 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>		95		
Gate to collector charge	]	Q <sub>gc</sub>		178		
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>		360		ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 40 \text{ A}$ $R_{g} = 10 \Omega$	t <sub>f</sub>		130		
Turn-off switching loss	V <sub>GE</sub> = 0 V/ 15V	E <sub>off</sub>		1.40		mJ
Turn-off delay time	T <sub>J</sub> = 125°C	t <sub>d(off)</sub>		380		ns
Fall time	$V_{CC} = 600 \text{ V, I}_{C} = 40 \text{ A}$ $R_{a} = 10 \Omega$	t <sub>f</sub>		185		
Turn-off switching loss	V <sub>GE</sub> = 0 V/ 15V	E <sub>off</sub>		2.6		mJ
DIODE CHARACTERISTIC						
Forward voltage	V <sub>GE</sub> = 0 V, I <sub>F</sub> = 40 A V <sub>GE</sub> = 0 V, I <sub>F</sub> = 40 A, T <sub>J</sub> = 150°C	V <sub>F</sub>		1.6 1.8	1.8	V

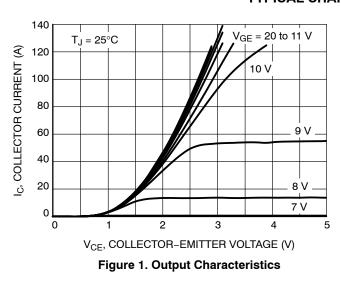
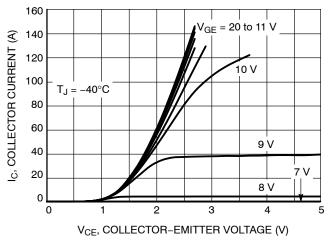


Figure 2. Output Characteristics



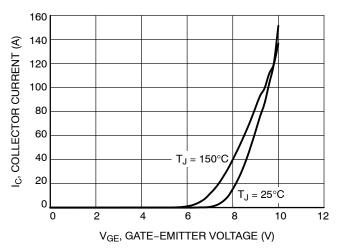
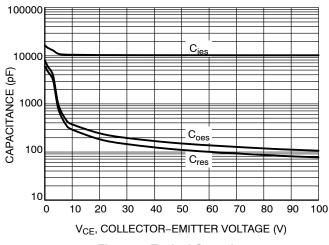


Figure 3. Output Characteristics

**Figure 4. Typical Transfer Characteristics** 



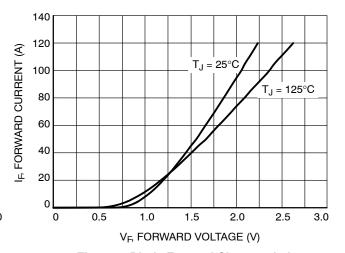
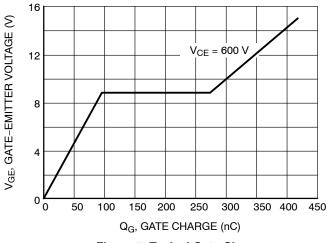


Figure 5. Typical Capacitance

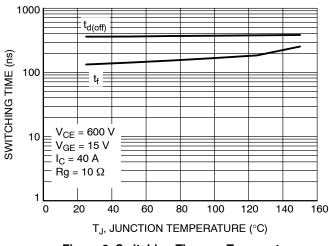
Figure 6. Diode Forward Characteristics



(m) 3.5 V<sub>CE</sub> = 600 V Eoff, TURN-OFF SWITCHING LOSS 3  $V_{GE} = 15 V$  $I_{C} = 40 \text{ A}$ 2.5  $Rg = 10 \Omega$ 2 1.5 0.5 0 0 140 100 120 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 7. Typical Gate Charge

Figure 8. Energy Loss vs. Temperature



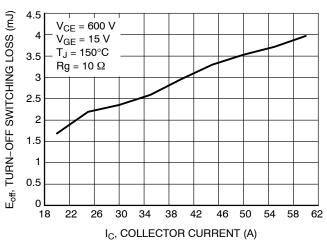
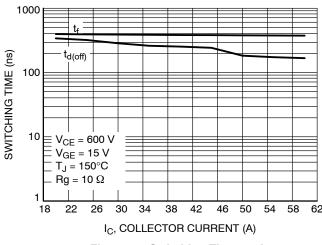


Figure 9. Switching Time vs. Temperature

Figure 10. Energy Loss vs. I<sub>C</sub>



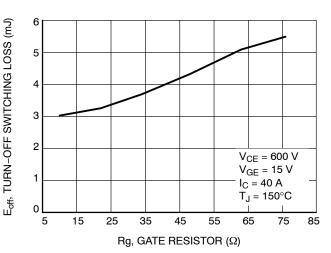


Figure 11. Switching Time vs. I<sub>C</sub>

Figure 12. Energy Loss vs. Rg

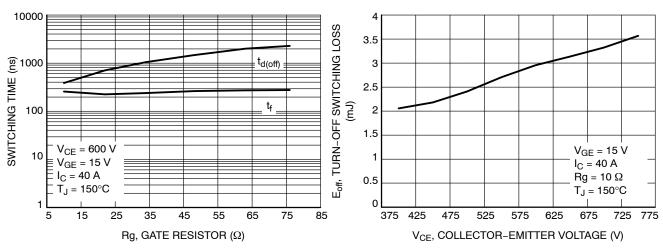


Figure 13. Switching Time vs. Rg

Figure 14. Energy Loss vs. V<sub>CE</sub>

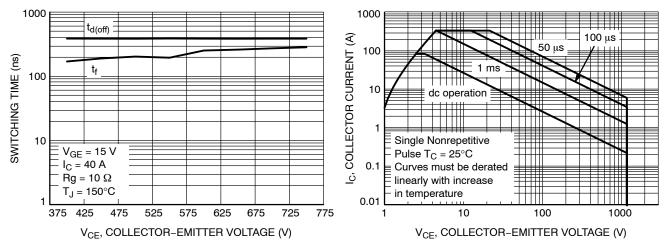


Figure 15. Switching Time vs. V<sub>CE</sub>

Figure 16. Safe Operating Area

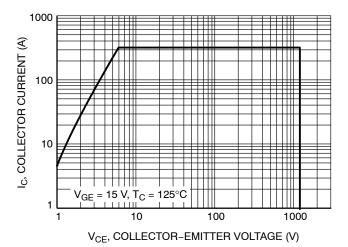


Figure 17. Reverse Bias Safe Operating Area

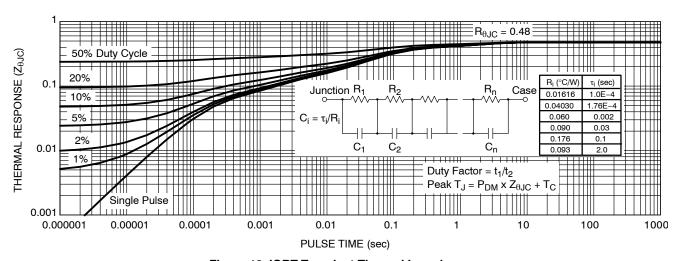


Figure 18. IGBT Transient Thermal Impedance

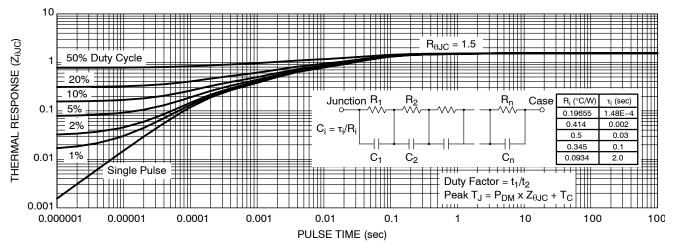


Figure 19. Diode Transient Thermal Impedance

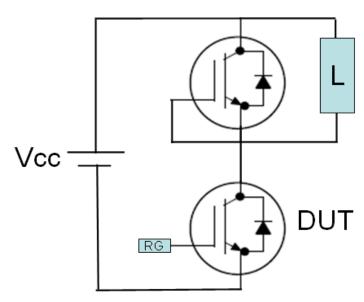


Figure 20. Test Circuit for Switching Characteristics

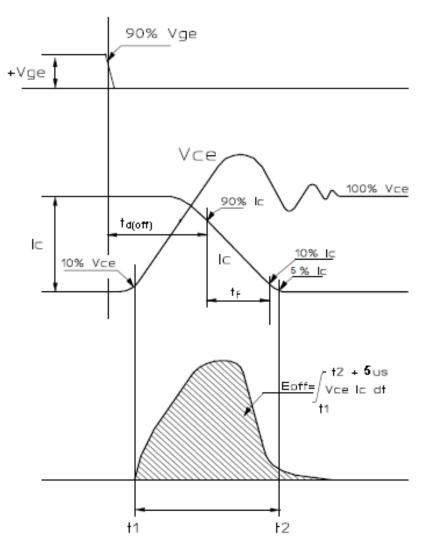
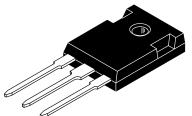


Figure 21. Definition of Turn Off Waveform





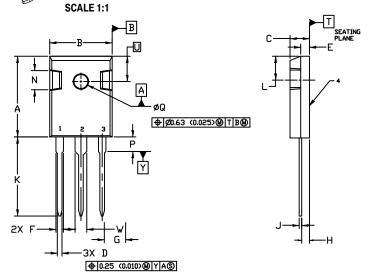
TO-247 CASE 340L ISSUE G

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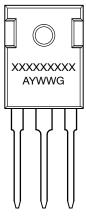
#### NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	CHES	
DIM	MIN.	MAX.	MIN.	MAX.	
Α	20.32	21.08	0.800	0.830	
В	15.75	16.26	0.620	0.640	
С	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Ε	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45 BSC		0.215 BSC		
Н	1.50	2.49	0.059	0.098	
J	0.40	0.80	0.016	0.031	
К	19.81	20.83	0.780	0.820	
L	5.40	6.20	0.212	0.244	
N	4.32	5.49	0.170	0.216	
Р		4.50		0.177	
Q	3.55	3.65	0.140	0.144	
U	6.15 BSC		0.242	BSC	
W	2.87	3.12	0.113	0.123	



# GENERIC MARKING DIAGRAM\*



STYLE 1:	
PIN 1.	GATE
2.	DRAIN
3.	SOURCE
4.	DRAIN

STYLE 2:
PIN 1. ANODE
2. CATHODE (S)
3. ANODE 2
4. CATHODES (S)

STYLE 3:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

XXXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

 STYLE 5:
 STYLE 6:

 PIN 1. CATHODE
 PIN 1. MAIN TERMINAL 1

 2. ANODE
 2. MAIN TERMINAL 2

 3. GATE
 3. GATE

 4. ANODE
 4. MAIN TERMINAL 2

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

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 APT15GT120BRG
 APT20GT60BRG
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 IXA30RG1200DHGLB

 IXA40RG1200DHGLB
 APT70GR65B2DU40
 NTE3320
 IHFW40N65R5SXKSA1
 APT70GR120J
 APT35GP120JDQ2

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 IKFW75N65ES5XKSA1
 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
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 XD15H120CX1
 XD25H120CX0
 XP15PJS120CL1B1

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 IHW20N120R5XKSA1
 RJH60D2DPP-M0#T2
 IKP20N60TXKSA1

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 IDW40E65D2FKSA1